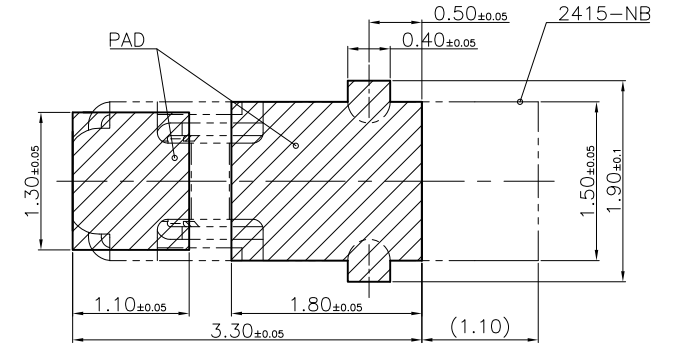
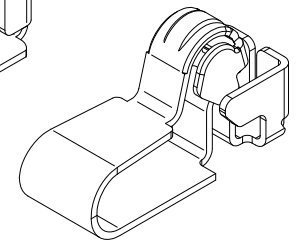
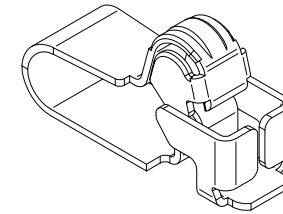
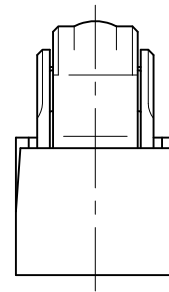
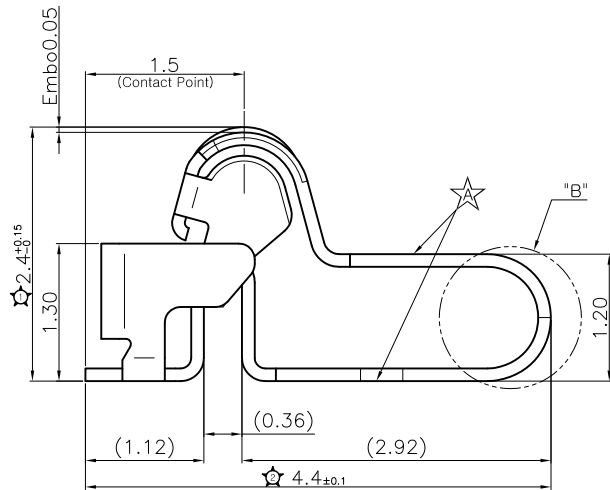


SIMULATION

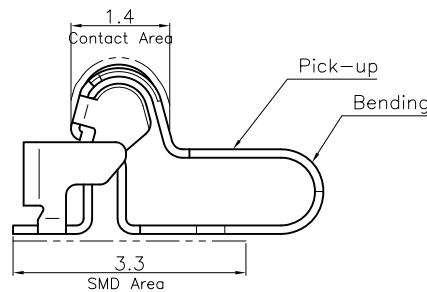


RECOMMENDED PCB LAYOUT (Top View)



**\*NOTE**

1. PLATING
  - Contact Area : Au 0.1  $\mu$ m Min over Ni 1.5~4.0  $\mu$ m.
  - SMD Area : Au 0.05  $\mu$ m Min over Ni 1.50~4.0  $\mu$ m.
  - Bending & Pick-up : Ni 1.5~3.5  $\mu$ m.
2. ☆ : C.T.Q
3. ☆ : 평탄도 0.05 Max.
4. Contact 가동거리(Max)는 0.6mm 이상으로 한다.
5. Contact 가동거리 : 1.0mm  
권장 Contact 높이 : 가동거리의 60~80% 범위 내 (0.60~0.80mm) => (1.60~1.80mm)
6. 제품의 안정적 Contact을 위하여 Bending部 "B" 주위에 기구적인 간섭이 없을 것.
7. 일반 공차 ±0.1 적용 할 것.



PLATING AREA

|                   |              |                   |              |               |
|-------------------|--------------|-------------------|--------------|---------------|
| 1                 | Contact      | Ti-Cu             | Note.1       | t0.12         |
| No                | Descriptions | Material          | Finish       | Remarks       |
| General Tolerance |              | Scale             | N/S          | Units         |
| Dimension         |              | Date              | 2013. 07. 16 | Sheet         |
| X                 |              | 1 of 1            |              | TITLE         |
| X.X               |              | Drawn             | Design       | Checked       |
| X.XX              |              | J.S. Kim          | 2013/08/20   | -             |
| X.XXX             |              | Y.J. Park         | 2013/08/20   | S.K. Hong     |
| ANGLE             |              | HYUPJIN CONNECTOR |              | SW No.        |
|                   |              |                   |              | DWG No.       |
|                   |              |                   |              | HJ-2415-NB-A1 |
|                   |              |                   |              | Rev.          |
|                   |              |                   |              | 0             |